Overview

HP ProBook 445 G7 Notebook PC

Left

1. Internal Microphones (2)
2. Webcam
3. Privacy Shutter (Only available with webcam)
4. Webcam LED
5. Clickpad
6. Hard Drive LED

7. SD Card Reader
8. Thermal Vent
9. USB 2.0 Port
10. Standard Security Lock Slot (Lock sold separately)
11. Power Button

Not all configuration components are available in all regions/countries.
c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020

Page 1

Overview

Right

1. Power Connector
2. USB Type-C® 3.1 Gen 1 Port
3. Ethernet Port (RJ-45)
4. HDMI Port (Cable not included)

5. USB 3.1 Gen 1 Port
6. USB 3.1 Gen 1 Port
7. Headphone / Microphone Combo Jack
8. HP Fingerprint Sensor (select models)

Not all configuration components are available in all regions/countries.
c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020

Page 2

Overview

At a Glance

- Preinstalled Windows 10 or FreeDOS
- Choice of AMD Ryzen™ 4000 series mobile processors, R7, R5 and R3
- Display include your choice of 35.56 cm (14.0") diagonal HD, Ultra Wide Viewing Angle FHD, And Privacy Panel option
- Enhanced security features including TPM2.0, HP Sure Sense, HP Sure Start, HP BIOSphere, Hardware enforced Firmware Protection, optional Fingerprint sensor (select models)[4], optional IR camera, and optional Privacy Panel
- Designed to pass MIL-STD 810H testing[1]
- Weight starting at 3.53 lb (1.6kg) (Weight will vary by configuration)
- HP Long-Life Rechargeable battery, with HP Fast Charge Technology recharges 50% in 30 minutes[2]
- Up to 512 GB Solid State Drives and 1 TB Hard Drive
- Up to 16 GB total system memory
- 720p HD webcam, IR camera for face authentication with Windows Hello
- Spill-resistant and optional backlit Keyboard[3], and Clickpad with multi-touch gestures enabled, taps enabled as default

1. MIL STD 810H testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Damage under the MIL STD test conditions or any accidental damage requires an optional HP Accidental Damage Protection Care Pack.
2. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode when used with the power adapter provided with the notebook. After charging has reached 50% capacity, charging speed will return to normal. Charging time may vary +/-10% due to System tolerance.
3. Backlit keyboard is an optional feature that must be configured at purchase.
4. HP Fingerprint Sensor is an optional feature and requires configuration at purchase.

   NOTE: See important legal disclosures for all listed specs in their respective features sections.

Technical Specifications

PRODUCT NAME

HP ProBook 445 G7 Notebook PC

OPERATING SYSTEMS

Preinstalled   Windows® 10 Pro 64[1]
Windows® 10 Pro 64 (National Academic License)[2]
Windows® 10 Home 64[1]
Windows® 10 Home Single Language 64[1]
Windows® 10 Enterprise 64 (Web Support)[1]
FreeDOS

1. Not all features are available in all editions or versions of Window. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.
2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282

PROCESSORS

AMD Ryzen™ 3 4300U APU with AMD Radeon™ Graphics (2.7 GHz base clock, up to 3.7 GHz max boost clock, 4 MB L3 cache, four-cores)[3,4,5,6]
AMD Ryzen™ 5 4500U APU with AMD Radeon™ Graphics (2.3 GHz base clock, up to 4.0 GHz max boost clock, 8 MB L3 cache, six-cores)[3,4,5,6]
AMD Ryzen™ 7 4700U APU with AMD Radeon™ Graphics (2.0 GHz base clock, up to 4.1 GHz max boost clock, 8 MB L3 cache, eight-cores)[3,4,5,6]

Processors Family
AMD Ryzen™ 4000 Series Mobile processors[6]

3. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
4. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. AMD's numbering is not a measurement of clock speed.
5. AMD Max Burst frequency performance varies depending on hardware, software and overall system configuration.
6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

QuickSpecs

HP ProBook 445 G7 Notebook PC

Technical Specifications

CHIPSET

Chipset is integrated with processor

GRAPHICS

Integrated
AMD Radeon™ Graphics[7]

Note: View processor section for details.

Supports
Support HD decode, DX12, HDMI 1.4

7. HD content required to view HD images.

DISPLAYS

Internal
Non-Touch
35.56 cm (14") diagonal HD SVA eDP anti-glare LED backlit slim, 220 cd/m², 45% NTSC (1366 x 768)[7,8]
35.56 cm (14") diagonal HD SVA eDP anti-glare LED backlit slim, 220 cd/m², 45% NTSC for HD camera (1366 x 768) [7,8]
35.56 cm (14") diagonal HD SVA eDP anti-glare LED backlit slim, 220 cd/m², 45% NTSC for HD + IR camera (1366 x 768) [7,8]
35.56 cm (14") diagonal FHD IPS eDP anti-glare LED-backlit slim, 250 cd/m², 45% NTSC (1920 x 1080) [7,8]
35.56 cm (14") diagonal FHD IPS eDP anti-glare LED-backlit slim, 250 cd/m², 45% NTSC for HD camera (1920 x 1080) [7,8]
35.56 cm (14") diagonal FHD IPS eDP anti-glare LED-backlit slim, 250 cd/m², 45% NTSC for HD + IR camera (1920 x 1080) [7,8]
35.56 cm (14") diagonal FHD eDP+PSR anti-glare LED-backlit flat, 1000 cd/m², 72% NTSC for HD Webcam Privacy (1920x1080) [7,8,9]

Supports narrow bezel

HDMI
HDMI 1.4 up to 4K 30Hz

7. HD content required to view HD images.
8. Resolutions are dependent upon monitor capability, and resolution and color depth settings.
9. HP Sure View integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.

Not all configuration components are available in all regions/countries.
c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020
Page 5

Technical Specifications

STORAGE AND DRIVES

Primary Storage
500 GB 7200 rpm SATA[10]
1 TB 5400 rpm SATA[10]

Primary M.2 Storage
128 GB SATA TLC Solid State Drive[10]
256 GB PCIe® NVMe™ Value Solid State Drive[10]
512 GB PCIe® NVMe™ TLC Solid State Drive[10]
512 GB PCIe® NVMe™ Value Solid State Drive[10]

Note: PCIe SSD not available for Celeron

10. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

MEMORY

Maximum Memory
16 GB DDR4-3200 SDRAM[11]

Memory
16 GB DDR4-3200 SDRAM (1 x 16 GB)
12 GB DDR4-3200 SDRAM (1 x 4 GB and 1 x 8 GB)[11]
8 GB DDR4-3200 SDRAM (1 x 8 GB)
8 GB DDR4-3200 SDRAM (2 x 4 GB)[11]
4 GB DDR4-3200 SDRAM (1 x 4 GB)

Memory Slots
2 SODIMM
Both slots are customer accessible / upgradeable by IT or self-maintainers only
DDR4 PC4 SODIMMS, system runs at 3200
Supports Dual Channel Memory

11. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WLAN
Realtek RTL8822CE 802.11 a/b/g/n/ac (2x2) Wi-Fi® + Bluetooth® 5 Combo[12]
Intel® Dual Band Wi-Fi® 6 AX200 802.11ax (2x2) and Bluetooth® 5 Combo, non-vPro™[12]
Intel® Dual Band Wireless-AC 9260 802.11 a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 5 Combo, non-vPro™[12]

Ethernet
Realtek RTL8111EP 10/100/1000 NIC[13]

12. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported.

Technical Specifications

13. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

AUDIO/MULTIMEDIA

Audio
Integrated microphone (Mono or Dual Array)
2 Integrated stereo speakers

Camera
720p HD camera[7]
720p HD + IR camera[7,14]

7. HD content required to view HD images.
14. IR camera is an optional feature that must be configured at purchase.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard
HP Premium Keyboard, spill-resistant with optional backlit[15]

Pointing Device
Clickpad with multi-touch gesture support

Function Keys
F1 - Display Switching
F2 - Blank or SureView On/Off
F3 - Brightness Down
F4 - Brightness Up
F5 - Audio Mute
F6 - Volume Down
F7 - Volume Up
F8 - Mic Mute
F9 - Blank or Backlit Toggle
F10 - numlk
F11 - Wireless
F12 - Sleep

Hidden Function Keys
Fn+R - Break
Fn+S - Sys Rq
Fn+C - Scroll Lock

15. Backlit keyboard is an optional feature that must be configured at purchase.

Not all configuration components are available in all regions/countries.
c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020

Page 7

Technical Specifications

SOFTWARE AND SECURITY

BIOS

HP BIOSphere Gen5[16]

HP Drive Lock & Automatic Drive Lock[17]

BIOS Update via Network

Master Boot Record Security

Power On Authentication

Secure Erase[18]

Absolute Persistence Module[19]

Pre-boot Authentication

Software

HP Connection Optimizer

HP Image Assistant

HP Hotkey Support

HP JumpStarts

HP Support Assistant[20]

HP Noise Cancellation Software

Buy Office (sold separately)

Manageability Features

HP Driver Packs[21]

HP System Software Manager (SSM)

HP BIOS Config Utility (BCU)

HP Client Catalog

HP Manageability Integration Kit Gen3[22]

Client Security Software

HP Client Security Manager Gen5[23]

HP Fingerprint Sensor[24]

Windows Defender[25]

Security Management

Pre-boot Authentication

TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified)

USB enable/disable (via BIOS)

Power-on password (via BIOS)

Setup password (via BIOS)

HP Fingerprint Sensor[24]

Support for chassis padlocks and cable lock devices

HP Sure Click[26]

HP Sure Sense[27]

Not all configuration components are available in all regions/countries.
c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020

Page 8

Technical Specifications

HP Sure Start Gen5[28]

16. HP BIOSphere Gen5 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.
17. HP Drive Lock & Automatic Drive Lock is not supported on NVMe drives
18. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
19. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
20. HP Support Assistant requires Windows and Internet access.
21. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
22. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
23. HP Client Security Manager Gen5 requires Windows and is available on the select HP Pro and Elite PCs. See product specifications for details.
24. HP Fingerprint Sensor is an optional feature and requires configuration at purchase.
25. Windows Defender Opt in and internet connection required for updates.
26. HP Sure Click is available on select HP platforms and supports Microsoft® Internet Explorer, Google Chrome, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode. Check http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=4AA7-0922ENW for all compatible platforms as they become available.
27. HP Sure Sense requires Windows 10. See product specifications for availability.
28. HP Sure Start Gen5 is available on select HP PCs with Intel processors. See product specifications for availability.

Technical Specifications

POWER

Power Supply
HP Smart 65 W External AC power adapter[29]
HP Smart 65 W EM External AC power adapter[29]
HP Smart 65 W USB Type-C® adapter[29]
HP Smart 45 W External AC power adapter[29]
HP Smart 45 W USB Type-C® adapter[29]

Primary Battery
HP Long Life 3-cell, 45 Wh Li-ion polymer[30]

Power Cord
3-wire plug - 1.8 m[29]
3-wire plug - 1.0 m[29]
2-wire plug - 1.0 m[29]
Duckhead power cord - 1.0 m[29]
Duckhead power cord - 1.8 m[29]

Battery life
15 hours and 15 minutes[31]

Battery Weight
0.22 kg
0.49 lb

29. Availability may vary by country.
30. Battery is internal and not replaceable by customer. Serviceable by warranty.
31. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.

WEIGHTS & DIMENSIONS

Product Weight
Starting at 3.53 lb[32]
Starting at 1.6 kg[32]

Product Dimensions (w x d x h)
12.76 x 9.36 x 0.71 in
32.42 x 23.77 x 1.79 cm

32. Weight will vary by configuration. Does not include power adapter.

PORTS/SLOTS

1 USB 3.1 Type-C® Gen 1 (Power delivery, DisplayPort™)
2 USB 3.1 Gen 1
1 USB 2.0 (powered port)
1 HDMI 1.4[33]
1 RJ-45
1 AC power

Not all configuration components are available in all regions/countries.
c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020

Page 10

Technical Specifications

1 stereo headphone/microphone combo jack

Expansion Slots
1 SD
Supports SD, SDHC, SDXC

33. HDMI cable sold separately.

ENVIRONMENTAL & INDUSTRY

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: •IT ECO declaration •US ENERGY STAR® •EPEAT® 2019 Gold in U.S. Based on US EPEAT® registration according to IEEE 1680.1–2018 EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.net for more information.		
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".		
Energy Consumption (in accordance with US ENERGY STAR® test method)	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)	4.14 W	4.164 W	4.056 W
Normal Operation (Long idle)	2.112 W	2.184 W	2.076 W
Sleep	0.372 W	0.384 W	0.372 W
Off	0.192 W	0.228 W	0.192 W
	Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.		
Heat Dissipation*	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)	14 BTU/hr	14 BTU/hr	14 BTU/hr
Normal Operation (Long idle)	7 BTU/hr	7 BTU/hr	7 BTU/hr
Sleep	1 BTU/hr	1 BTU/hr	1 BTU/hr
Off	1 BTU/hr	1 BTU/hr	1 BTU/hr
	Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.		
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L_{WAd}, bels)		Sound Pressure (L_{pAm}, decibels)
Typically Configured – Idle	2.5		25

Technical Specifications

Fixed Disk – Random writes	2.5		25
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: • 3 USB ports • 1 PC card slot (type I/II) • 1 ExpressCard/54 slot • 1 IEEE 1394 Port • 2 SODIMM memory slots • Optional expansion base docking station • 1 multi-bay II storage port • Interchangeable HDD Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.		
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Battery size: Not Applicable Battery type: Not Applicable		
Additional Information	• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • This product is in compliance with the IEEE 1680.1 (EPEAT) standard at the <Gold> level, see http://www.epeat.net • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains 2.4% post-consumer recycled plastic (by wt.) • This product is 96.2% recycle-able when properly disposed of at end of life.		
Packaging Materials	**External:**	PAPER/Paper	51 g
		PAPER/Corrugated	230 g
	Internal:	PLASTIC/Polyethylene Expanded - EPE	31 g
		PLASTIC/Polyethylene low density - LDPE	9 g
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes		

Technical Specifications

	• Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging: • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP Inc. Corporate Environmental Information	For more information about HP's commitment to the environment: Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K _Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

Not all configuration components are available in all regions/countries.

c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020   Page 13

Technical Specifications

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)

Nominal Operating Voltage	19V
Average Operating Power	7.52 W
Integrated graphics	Yes (AMD Radeon™ Graphics)
Max Operating Power	Discrete < 65W UMA < 45W

Temperature

Operating	32° to 95° F (0° to 35° C) (not writing optical)
Non-operating	41° to 95° F (5° to 35° C) (writing optical)

Relative Humidity

Operating	10% to 90%, non-condensing
Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

Shock

Operating	40 G, 2 ms, half-sine
Non-operating	200 G, 2 ms, half-sine

Random Vibration

Operating	0.75 grms
Non-operating	1.50 grms

Altitude (unpressurized)

Operating	-50 to 10,000 ft (-15.24 to 3,048 m)
Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)

Planned Industry Standard Certifications

UL	Yes
CSA	Yes
FCC Compliance	Yes
ENERGY STAR®	Selected models[34]
EPEAT® 2019	Yes, Gold in U.S.[35]
ICES	Yes
Australia	Yes
NZ A-Tick Compliance	Yes
CCC	Yes
Japan VCCI Compliance	Yes
KC	Yes
BSMI	Yes
CE Marking Compliance	Yes
BNCI or BELUS	Yes
CIT	Yes
GOST	Yes

Not all configuration components are available in all regions/countries.
c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020

Page 14

Technical Specifications

Saudi Arabian Compliance (ICCP)	Yes
SABS	Yes

34. Configurations of the HP ProBook 445 G7 that are ENERGY STAR® qualified are identified as HP ProBook 445 G7 ENERGY STAR on HP websites and on http://www.energystar.gov.

35. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit http://www.epeat.net for more information.

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Panel LCD 14 inch diagonal HD (1366 x 768) Anti-Glare WLED SVA 45% NTSC 220 nits eDP 1.2 w/o PSR slim NB non-touch	Outline Dimensions (W x H x D)	316.2 x 198.04 (max.)
	Active Area	309.4 x 173.95
	Weight	<280 g max.
	Diagonal Size	14.0 (inch)
	Thickness	3.0 mm max
	Interface	eDP 1.2 (1 lane)
	Surface Treatment	Anti-Glare
	Touch Enabled	No
	Contrast Ratio	300:1 (typ)
	Refresh Rate	60 Hz
	Brightness	220 nits typical (Panel Only)
	Pixel Resolution	1366 x 768 (HD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
	Color Gamut Coverage	45% of NTSC
	Color Depth	6 bits + Hi FRC
	Viewing Angle	SVA 40/40/15/30

Panel LCD 14 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 45% NTSC 250 nits eDP slim NB	Outline Dimensions (W x H x D)	316.17 x 197.98 mm (max)
	Active Area	309.37 x 174.02 mm (typ.)
	Weight	285 g (max)
	Diagonal Size	14.0 inch
	Thickness	3.0 mm (max)
	Interface	eDP 1.2 (2 lane)
	Surface Treatment	Anti-Glare
	Touch Enabled	No
	Contrast Ratio	600:1 (typ.)
	Refresh Rate	60 Hz
	Brightness	250 nits
	Pixel Resolution	1920 x 1080 (FHD)
	Format of LCD Pixel Arrangement	RGB

Not all configuration components are available in all regions/countries.
c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020

Page 15

Technical Specifications

	Backlight	LED
	Color Gamut Coverage	45% of NTSC
	Color Depth	6 bits
	Viewing Angle	UWVA 85/85/85/85

Panel LCD 14 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 72% NTSC 1000 nits eDP 1.4+PSR2 flat Privacy	**Outline Dimensions (W x H x D)**	315.31 x 195.498 mm (max)
	Active Area	309.312 x 173.988 mm (typ.)
	Weight	265 g (max)
	Diagonal Size	14 inch
	Thickness	3.0 mm (max)
	Interface	eDP 1.4 + PSR2 (4 lane)
	Surface Treatment	Anti-Glare
	Touch Enabled	No
	Contrast Ratio	2000:1 (typ.)
	Refresh Rate	60 Hz
	Brightness	1000 nits
	Pixel Resolution	1920 x 1080 (FHD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
	Color Gamut Coverage	72% of NTSC
	Color Depth	8 bit

STORAGE AND DRIVES

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software

500 GB 7200 rpm SATA Hard Drive	**Drive Weight**	0.20 lbs (92 g) ~ 0.21 lbs (95 g)
	Rotation Speed	7200 rpm
	Cache Buffer	Up to 32 MB
	Height	0.28 in (7 mm)
	Width	2.75 in (69.85 mm)
	Interface	ATA-8, SATA 3.0
	Transfer Rate	600 MB/s
	Seek Time	Single Track: 2 ~ 1.5 ms Average: 11 ~ 13 ms Maximum: 18 ~ 22 ms
	Logical Blocks	976,773,168
	Operating Temperature	32° to 140° F (0° to 60° C) [top cover temp]
	Security Features	ATA Security
	Features	S.M.A.R.T., NCQ, Ultra DMA

Not all configuration components are available in all regions/countries.
c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020

Page 16

Technical Specifications

1 TB 5400 rpm SATA Hard Drive	Drive Weight	0.21 lbs (94 g)
	Rotation Speed	5400 rpm
	Cache Buffer	Up to 32 MB
	Height	0.28 in (7.2 mm)
	Width	2.75 in (69.85 mm)
	Interface	ATA-8, SATA 3.0
	Transfer Rate	600 MB/s
	Seek Time	Single Track2 ms Average12 ~ 13 ms Maximum18 ~ 22 ms
	Logical Blocks	1,953,525,168
	Operating Temperature	32° to 140° F (0° to 60° C) [top cover temp]
	Security Features	ATA Security
	Features	S.M.A.R.T., NCQ, Ultra DMA

SSD 128 GB 2280 M2 SATA-3 TLC	Form Factor	M.2 2280
	Capacity	128 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	ATA-8, SATA 3.0
	Maximum Sequential Read	Up To 520 MB/s
	Maximum Sequential Write	Up To 450 MB/s
	Logical Blocks	250,069,680
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	DIPM; TRIM; DEVSLP

256 GB 2280 PCIe NVMe Value Solid State Drive	Form Factor	M.2 2280
	Capacity	256 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe Gen3
	Maximum Sequential Read	Up To 1700 MB/s
	Maximum Sequential Write	Up To 1300 MB/s
	Logical Blocks	500,118,192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	TRIM; L1.2

Not all configuration components are available in all regions/countries.
c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020

Page 17

Technical Specifications

512 GB 2280 M2 PCIe NVMe TLC Solid State Drive	Form Factor	M.2 2280
	Capacity	512 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Up To 2600 MB/s
	Maximum Sequential Write	Up To 1400 MB/s
	Logical Blocks	1,000,215,216
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	TRIM; L1.2

512 GB 2280 PCIe NVMe Value Solid State Drive	Form Factor	M.2 2280
	Capacity	512 GB
	NAND Type	Value
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Up To 1500 ~ 1700 MB/s
	Maximum Sequential Write	Up To 860 ~ 1500 MB/s
	Logical Blocks	1,000,215,216
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security, TRIM; L1.2

NETWORKING/COMMUNICATIONS

WLAN

Intel® Wi-Fi 6[1] AX200 and Bluetooth® 5.0 802.11ax (2x2) non-vPro, supporting gigabit file transfer speeds) non-vPro	Wireless LAN Standards	IEEE 802.11a
		IEEE 802.11b
		IEEE 802.11g
		IEEE 802.11n
		IEEE 802.11ac
		IEEE 802.11ax
		IEEE 802.11d
		IEEE 802.11e
		IEEE 802.11h
		IEEE 802.11i
		IEEE 802.11k
		IEEE 802.11r
		IEEE 802.11v
	Interoperability	Wi-Fi CERTIFIED™
	Frequency Band	•802.11b/g/n/ax 2.402 – 2.482 GHz

Not all configuration components are available in all regions/countries.
c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020

Page 18

Technical Specifications

	•802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
Data Rates	•802.11b: 1, 2, 5.5, 11 Mbps •802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) •802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) • 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security[3]	•IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only •AES-CCMP: 128 bit in hardware •802.1x authentication •WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. •WPA2 certification •IEEE 802.11i •WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power[2]	• 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum • 802.11ax HT40(2.4GHz): +10dBm minimum • 802.11ax VHT160(5GHz): +10dBm minimum
Power Consumption	•Transmit mode 2.0 W •Receive mode 1.6 W •Idle mode (PSP) 180 mW (WLAN Associated) •Idle mode 50 mW (WLAN unassociated) •Connected Standby 10mW •Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity[4]	•802.11b, 1Mbps: -93.5dBm maximum •802.11b, 11Mbps: -84dBm maximum • 802.11a/g, 6Mbps: -86dBm maximum • 802.11a/g, 54Mbps: -72dBm maximum • 802.11n, MCS07: -67dBm maximum • 802.11n, MCS15: -64dBm maximum • 802.11ac, MCS0: -84dBm maximum • 802.11ac, MCS9: -59dBm maximum •802.11ax, MCS11(HT40): -59dBm maximum

Not all configuration components are available in all regions/countries.
c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020

Page 19

Technical Specifications

	•802.11ax, MCS11(VHT160): -58.5dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	Type 2230: 2.8 g Type 126: 1.3 g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (−10° to 70° C) Non-operating: −40° to 176° F (−40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing) Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m) Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF LED OFF – Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0/5.1 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps Signaling Data Rate 2.17 Mbps BLE: 1 Mbps Signaling Data Rate 0.2 Mbps 1. Actual throughput may vary. Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer

Not all configuration components are available in all regions/countries.
c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020

Page 20

Technical Specifications

LE Low Duty Cycle Directed Advertising
LE L2CAP Connection Oriented Channels
Train Nudging & Interlaced Scan
BT4.2 ESR08 Compliance
LE Secure Connection- Basic/Full
LE Privacy 1.2 –Link Layer Privacy
LE Privacy 1.2 –Extended Scanner Filter Policies
LE Data Packet Length Extension
FAX Profile (FAX)
Basic Imaging Profile (BIP)2
Headset Profile (HSP)
Hands Free Profile (HFP)
Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported.
2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of
transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
3. Check latest software/driver release for updates on supported security features.
4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Intel® 802.11a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 5.0 Combo[1] Non-vPro	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi CERTIFIED™
	Frequency Band	•802.11b/g/n 2.402 – 2.482 GHz •802.11a/n/ac 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
	Data Rates	•802.11b: 1, 2, 5.5, 11 Mbps •802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) •802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
	Modulation	Direct Sequence Spread Spectrum

Technical Specifications

	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security[3]	•IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only •AES-CCMP: 128 bit in hardware •802.1x authentication •WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. •WPA2 certification •IEEE 802.11i •WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power[2]	• 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum
Power Consumption	•Transmit mode 2.0 W •Receive mode 1.6 W •Idle mode (PSP) 180 mW (WLAN Associated) •Idle mode 50 mW (WLAN unassociated) •Connected Standby/Modern Standby: 10mW •Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity[4]	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum
Antenna type	High efficiency antenna. One embedded dual band 2.4/5 GHz antenna is provided to the card to support WLAN communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	Type 2230: 2.8 g Type 126: 1.3 g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (−10° to 70° C) Non-operating: −40° to 176° F (−40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing) Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m) Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF

Not all configuration components are available in all regions/countries.
c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020

Page 22

Technical Specifications

LED OFF – Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps Signaling Data Rate 2.17 Mbps BLE: 1 Mbps Signaling Data Rate 0.2 Mbps 1. Actual throughput may vary. Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Electrical Interface	USB 2.0 compliant
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited.
2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

Not all configuration components are available in all regions/countries.

c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020

Page 23

Technical Specifications

802.11 a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 5.0	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi CERTIFIED™
	Frequency Band	•802.11b/g/n 2.402 – 2.482 GHz •802.11a/n/ac 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
	Data Rates	•802.11b: 1, 2, 5.5, 11 Mbps •802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) •802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz)
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security[3]	•IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only •AES-CCMP: 128 bit in hardware •802.1x authentication •WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. •WPA2 certification •IEEE 802.11i •WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power[2]	• 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum
	Power Consumption	•Transmit mode: 2.0 W

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c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020

Page 24

Technical Specifications

	•Receive mode: 1.6 W •Idle mode (PSP) 180 mW (WLAN Associated) •Idle mode: 50 mW (WLAN unassociated) •Connected Standby/Modern Standby: 10mW •Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity[4]	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	Type 2230: 2.8 g Type 126: 1.3 g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (−10° to 70° C) Non-operating: −40° to 176° F (−40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing) Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m) Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF LED OFF – Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
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Signaling Data Rate	Legacy: 3 Mbps Signaling Data Rate 2.17 Mbps BLE: 1 Mbps Signaling Data Rate 0.2 Mbps 1. Actual throughput may vary. Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW

Not all configuration components are available in all regions/countries.
c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020

Page 25

Technical Specifications

	Selective Suspend 17 mW
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited.
2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
3. Check latest software/driver release for updates on supported security features.
4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Realtek RTK8111HSH 10/100/1000 Integrated NIC	**Connector**	RJ-45
	System Interface	PCIe + SMBus
	Ethernet Features	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
	Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption

Technical Specifications

	Advanced link down power saving for reducing link down power consumption
Performance Features	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K
Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
Management Interface	Auto MDI/MDIX Crossover cable detection

POWER

HP 45 W Smart AC Adapter	Dimensions (H x W x D)	3.74 x 1.57 x 1.04 in (9.5 x 4 x 2.65 cm)	
	Weight	0.386 lb (175 g) max Not including power cord. Power cord varies by country	
	Input	90 to 265 VAC	
		Input Efficiency	87.74% at 115VAC and 88.4% at 230VAC
		Input frequency range	47 to 63 Hz
		Input AC current	1.4 A at 90 VAC
	Output	**Output power**	45 W
		DC output	19.5 V
		Hold-up time	5 msec at 115 VAC input
		Output current limit	<8.0 A
	Connector	4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords	
	Environmental Design	**Operating temperature**	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	*CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.	

Dimensions	90 x 51 x 28.5 mm

Technical Specifications

	Weight	220 g +/- 10 g Not including power cord. Power cord varies by country	
	Input	**Input Efficiency**	88.0 % at 115 VAC and 89.0 % at 230VAC
		Input frequency range	47 ~ 63 Hz
		Input AC current	1.7 A at 90 VAC
	Output	**Output power**	65 W
		DC output	19.5 V
		Hold-up time	5 msec at 115 VAC input
		Output current limit	<11.0 A
HP 65 W Smart AC adapter	**Connector**	4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords	
	Environmental Design	**Operating temperature**	32°F to 95°F (0° to 35°C)
		Non-operating (storage) temperature	–4˚F to 185˚F (–20˚ to 85˚C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	*CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.	

HP 65W EM Smart AC adapter	**Dimensions**	102 x 55 x 30 mm	
	Weight	270 g +/- 10 g Not including power cord. Power cord varies by country	
	Input	**Input Efficiency**	87% min at 115V/230V
		Input frequency range	47 to 63 Hz
		Input AC current	1.7 A at 90 VAC and maximum load
	Output	**DC output**	65 W (19.5V/3.33A)
		Hold-up time	5 msec at 115 V input
		Output current limit	<11A, Over voltage protection- 29V max automatic shutdown
	Connector	4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords	
	Environmental Design	**Operating temperature**	32˚F to 95˚F (0˚ to 35˚C)
		Non-operating (storage) temperature	–4˚F to 185˚F (–20˚ to 85˚C)
		Altitude	0 to 5,000 m
		Humidity	0% to 95%
		Storage Humidity	0% to 95%

Not all configuration components are available in all regions/countries.
c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020

Page 28

Technical Specifications

EMI and Safety Certifications	*CE Mark - EMC directives *Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE; Reliability - failure rate of less than 0.1% annually within the first three years of operation. *MTBF - over 200,000 hours at 25°C ambient condition.	

AC Adapter 65 Watt nPFC USB Type-C®	**Dimensions**	74 x 74 x 28.5 mm	
	Weight	245 g +/- 10 g Not including power cord. Power cord varies by country	
	Input	**Input Efficiency**	81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 10V/5A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A
		Input frequency range	47 ~ 63 Hz
		Input AC current	1.7 A at 90 VAC and maximum load
	Output	**Output power**	65 W
		DC output	5V/9V/10V/12V/15V/20V
		Hold-up time	5ms at 115 VAC input
		Output current limit	<8.0 A
	Connector	USB Type-C®	
	Environmental Design	**Operating temperature**	32° F to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° F to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	5% to 95%
		Storage Humidity	5% to 95%
	EMI and Safety Certifications	*CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 100,000 hours at 25°C ambient condition.	

AC Adapter 45 Watt nPFC USB type C®	**Dimensions**	94.0 mm x 40.0 mm x 26.5 mm	
	Weight	192.5 g +/-10 g Not including power cord. Power cord varies by country	
	Input	**Input Efficiency**	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V: 81.5% 9V: 86.7% 12V: 87.41% 15V: 87.8%

Technical Specifications

	Input frequency range	47 ~ 63 Hz	
	Input AC current	Max. 1.4 A at 90 VAC	
Output	Output power	5V/15W 9V/27W 12V/36W 15V/45W	
	DC output	5V/9V/12V/15V	
	Hold-up time	5ms at 115 VAC input	
	Output current limit	<5.0 A	
Connector	USB Type-C®		
Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)	
	Non-operating (storage) temperature	–4°F to 185°F (–20° to 85°C)	
	Altitude	0 to 16,400 ft (0 to 5000m)	
	Humidity	20% to 95%	
	Storage Humidity	10% to 95%	
EMI and Safety Certifications	*CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE* MTBF - over 200,000 hours at 25°C ambient condition.		

3 Cell WHr 45 Long Life - Polymer HP Fast Charge Technology[1]	Dimensions (H x W x L)	6.0 x 184.7 x 88.9 mm	
	Weight	0.22 kg (0.48lb)	
	Cells/Type	3cell Lithium-Ion	
	Energy	Voltage	11.55 V
		Amp-hour capacity	3.900 Ah
		Watt-hour capacity	45 Wh
	Temperature	Operating (Charging)	32˚ to 113˚ F (0˚ to 45˚ C)
		Operating (Discharging)	14˚ to 122˚ F (–10˚ to 60˚ C)
	Optional Travel Battery Available	No	

1. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode when used with the power adapter provided with the notebook. After charging has reached 50% capacity, charging speed will return to normal. Charging time may vary +/-10% due to System tolerance.

Not all configuration components are available in all regions/countries.
c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020

Page 30

Technical Specifications

Country of Origin

China

Not all configuration components are available in all regions/countries.
c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020

Page 31

Options and Accessories (sold separately and availability may vary by country)

Type	Description	Part Number
Cases	HP Essential Top Load Case	H2W17AA
	HP Essential Backpack (up to 15.6")	H1D24AA
	HP 17.3 Business Backpack	2SC67AA
Docking	HP USB-C Mini Dock	1PM64AA
	HP Thunderbolt Dock 120W G2	2UK37AA
	HP TB Dock G2 w/ Combo Cable	3TR87AA
	HP TB Dock 120W G2 w/Audio	3YE87AA
	HP TB Dock 120W G2 Cable	3XB94AA
	HP TB Dock G2 Combo Cable	3XB96AA
	HP TB Dock G2 Audio Module	3AQ21AA
	HP USB-C/A Universal Dock G2	5TW13AA
	HP USB-C Dock G5	5TW10AA
Input / Output	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Bluetooth Travel Mouse	6SP30AA
	HP Ultra Mobile Wireless Mouse	H6F25AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP HDMI to DVI Adapter	F5A28AA
	HP Elite USB-C Hub	4WX89AA
	HP USB-C Travel Hub G2	7PJ38AA
Power	HP 45W Smart AC Adapter 4.5mm	H6Y88AA
	65W Smart Power Adapter (w/ 4.5mm to 7.5mm DC dongle)	H6Y89AA
	HP 65W Slim AC Adapter	H6Y82AA
	HP 65W USB-C Slim Power Adapter	3PN48AA
	HP 65W USB-C Power Adapter	1HE08AA
	HP 45W USB-C Power Adapter	1HE07AA
	HP USB-C Power Bank	2NA10AA
Storage	HP External USB Optical Drive	F2B56AA
Security	HP Keyed Cable Lock 10mm	T1A62AA
	HP Sure Key Cable Lock	6UW42AA
Displays	HP E223d Docking Monitor	5VT82A8/5VT82AA
	HP E243d Docking Monitor	1TJ76AA
	HP E273d Docking Monitor	5WN63A8/5WN63AA
	HP EliteDisplay E244d Monitor	6PA50A8/6PA50AA
	HP EliteDisplay E274d Monitor	6PA56A8/6PA56AA

Not all configuration components are available in all regions/countries.
c06543049 — DA 16569 - Worldwide — Version 3 — May 7, 2020

Page 32

Summary of Changes

Date of change:	Version History:		Description of change:
April 29, 2020	From V1 to V2	Updated	MIL-STD 810G to MIL-STD 810H
May 7, 2020	From V2 to V3	Updated	Ethernet Section